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(54) HOUSING ELEMENT FOR AN ELECTRONIC **CIRCUIT**

- (71) Applicant: TE Connectivity Solutions GmbH, Schaffhausen (CH)
- Inventors: Dirk DUENKEL, Bensheim (DE); Gregor PANITZ, Bensheim (DE)
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(57)ABSTRACT

A housing element for an electronic circuit includes a housing element body made from an insulating material with a through opening passing from a first side of the housing element body to a second side of the housing element body. An electrical contact passes through the opening. The electrical contact has a first contact element and a second contact element, wherein the first contact element is connected to the second contact element. The first contact element has a first direction of extent and the second contact element has a second direction of extent, wherein the first direction of extent and the second direction of extent have an angle of at least 45 degrees and no more than 135 degrees relative to each other.

